

IN THE SPECIFICATION:

Please revise paragraph 0027 as follows:

[0027] Fig. 3A is a top view of half of a quad flat package 300 in accordance with one embodiment of the present invention. Similar to the prior art package 200, package 300 comprises a semiconductor die 310, a die attach pad 330 below die 210 and encapsulant 350 surrounding die 310 and die attach pad 330. There are bondwires 380 inside encapsulant 350 electrically connecting bond pads on die 310 to a plurality of lead fingers 370 deployed on an edge of package 300. Of these lead fingers, at least finger 371 is a ground lead. Again, lead fingers (not shown) on the other edges of the package are also connected to bond pads on die 310 by bondwires (not shown). Fig. 3B is a side sectional view taken along lines B-B of Fig. 3A. Also shown in Fig. 3B is a cross-sectional view of a printed circuit board (PCB) 390 to which package 300 is attached. A conductive plane 391 made of a material such as copper is embedded in PCB 390.